BSS215PL6327HTSA1 Datasheet

DiGi Electronics Part Number	BSS215PL6327HTSA1-DG
Manufacturer	Infineon Technologies
Manufacturer Product Number	BSS215PL6327HTSA1
Description	MOSFET P-CH 20V 1.5A SOT23-3
Detailed Description	P-Channel 20 V 1.5A (Ta) 500mW (Ta) Surface Mount PG-SOT23

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
BSS215PL6327HTSA1	Infineon Technologies
Series:	Product Status:
OptiMOS™	Obsolete
FET Type:	Technology:
P-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
20 V	1.5A (Ta)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
2.5V, 4.5V	150mOhm @ 1.5A, 4.5V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
1.2V @ 11µA	3.6 nC @ 4.5 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±12V	346 pF @ 15 V
FET Feature:	Power Dissipation (Max):
-	500mW (Ta)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
PG-SOT23	TO-236-3, SC-59, SOT-23-3

Environmental & Export classification

Moisture Sensitivity Level (MSL):	REACH Status:
1 (Unlimited)	REACH Unaffected
ECCN:	HTSUS:
EAR99	8541.21.0095

BSS215P

OptiMOS™ P2 Small-Signal-Transistor

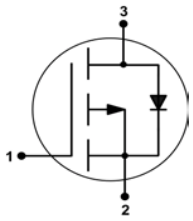
Features

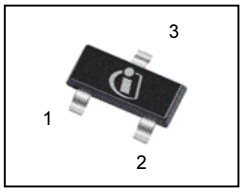
- P-channel
- Enhancement mode
- Super Logic Level (2.5V rated)
- Avalanche rated
- Qualified according to AEC Q101
- 100% lead-free; RoHS compliant

Product Summary

V_{DS}		-20	V
$R_{DS(on),max}$	V_{GS}=-4.5 V	150	mΩ
	V_{GS}=-2.5 V	280	
I_D		-1.5	A

PG-SOT23





Type	Package	Tape and Reel Information	Marking	Lead Free	Packing
BSS215P	PG-SOT23	L6327: 3000 pcs/ reel	YDs	Yes	Non dry

Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	T_A=25 °C	-1.5	A
		T_A=70 °C	-1.18	
Pulsed drain current	$I_{D,pulse}$	T_A=25 °C	-6	
Avalanche energy, single pulse	E_{AS}	I_D=-1.5 A, R_{GS}=25 Ω	11	mJ
Reverse diode dv/dt	dv/dt	I_D=-1.5 A, V_{DS}=-16V, di/dt=-200A/µs, $T_{j,max}$=150 °C	6	kV/µs
Gate source voltage	V_{GS}		±12	V
Power dissipation[1)]	P_{tot}	T_A=25 °C	0.5	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
ESD Class		JESD22-A114 -HBM	0 (<250V)	V
Soldering Temperature			260 °C	°C
IEC climatic category; DIN IEC 68-1			55/150/56	°C

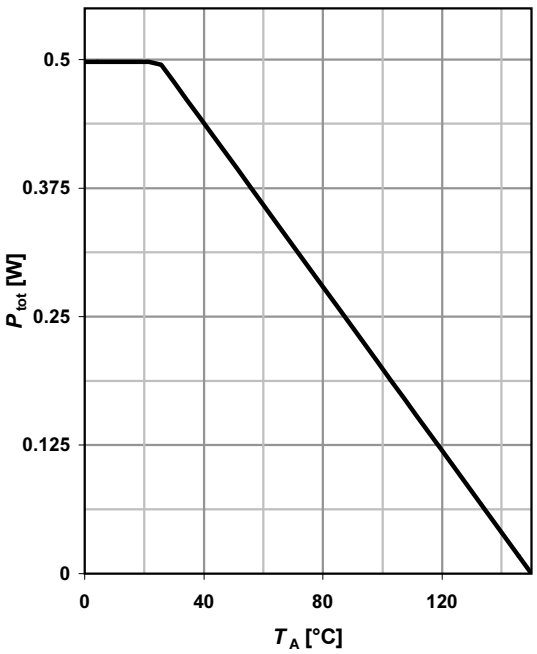
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - ambient	R_{thJA}	minimal footprint[1)]	-	-	250	K/W
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=-250 µA	-20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-11 µA	-1.2	-0.9	-0.6	
Drain-source leakage current	I_{DSS}	V_{DS}=-20V, V_{GS}=0 V, T_j=25 °C	-	-	-1	µA
		V_{DS}=-20V, V_{GS}=0V, T_j=150 °C	-	-	-100	
Gate-source leakage current	I_{GSS}	V_{GS}=-12V, V_{DS}=0V	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=2.5 V, I_D=-1.1 A	-	166	280	mΩ
		V_{GS}=4.5 V, I_D=-1.5 A	-	105	150	
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=1.18 A	-	4.5	-	S

[1)] Performed on 40mm^2 FR4 PCB. The traces are 1mm wide, 70µm thick and 20mm long; they are present on both sides of the PCB.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=-15 V, f=1 MHz	-	260	346	pF
Output capacitance	C_{oss}		-	102	135	
Reverse transfer capacitance	C_{rss}		-	85	128	
Turn-on delay time	$t_{d(on)}$	V_{DD}=-10 V, V_{GS}=-4.5 V, I_D=-1.5 A, R_G=6 Ω	-	6.7	-	ns
Rise time	t_r		-	9.7	-	
Turn-off delay time	$t_{d(off)}$		-	14.5	-	
Fall time	t_f		-	14.0	-	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=16 V, I_D=-1.5 A, V_{GS}=0 to -4.5 V	-	-0.49	-	nC
Gate to drain charge	Q_{gd}		-	-1.9	-	
Gate charge total	Q_g		-	-3.6	-	
Gate plateau voltage	$V_{plateau}$		-	-1.9	-	V
Reverse Diode						
Diode continous forward current	I_S	T_A=25 °C	-	-	-0.5	A
Diode pulse current	$I_{S,pulse}$		-	-	-6	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=-1.5 A, T_j=25 °C	-	-0.8	-1.1	V
Reverse recovery time	t_{rr}	V_R=10 V, I_F=-1.5 A, di_F/dt=100 A/µs	-	21.0	-	ns
Reverse recovery charge	Q_{rr}		-	-3.7	-	nC

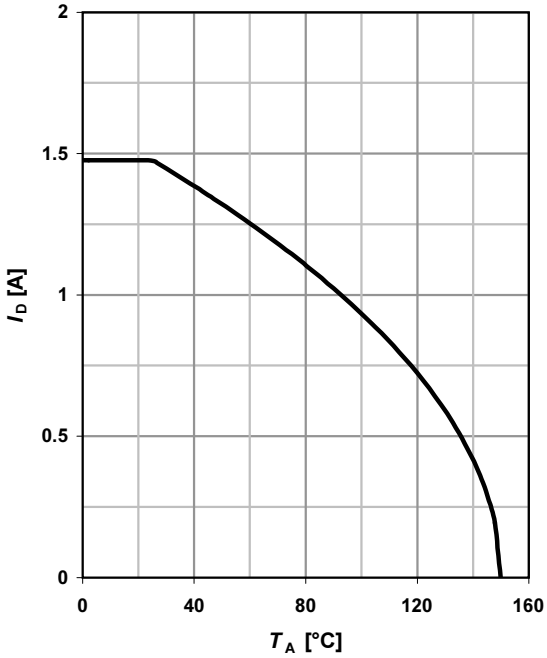
1 Power dissipation

$P_{tot}=f(T_A)$



2 Drain current

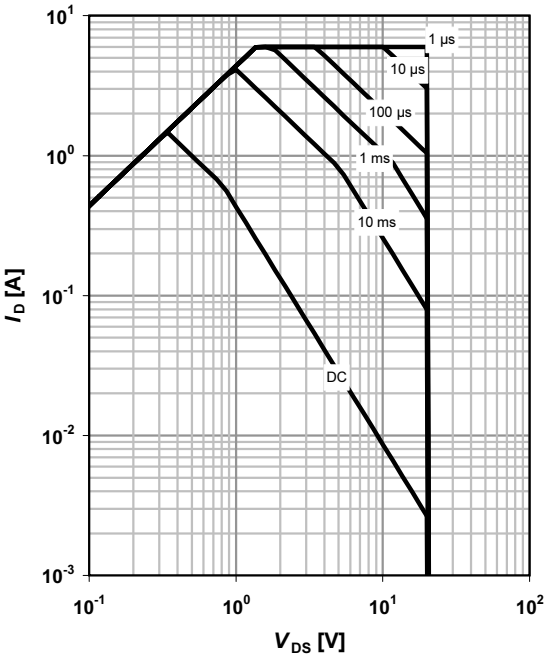
$I_D=f(T_A)$; $V_{GS}\leq$-4.5 V



3 Safe operating area

$I_D=f(V_{DS})$; T_A=25 °C; D=0

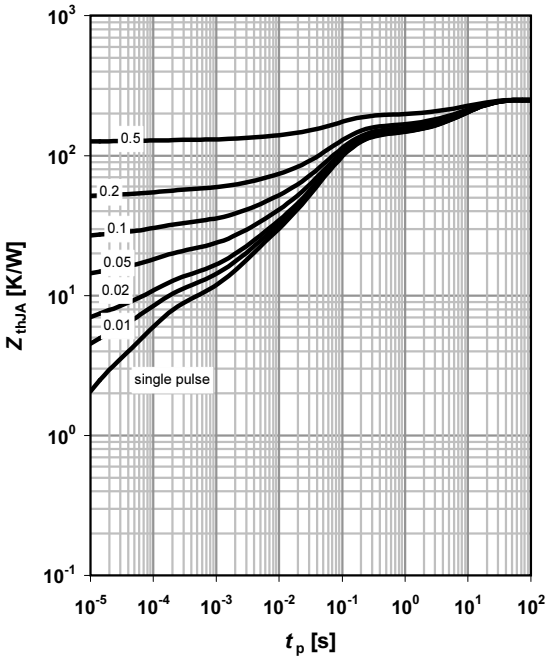
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJA}=f(t_p)$

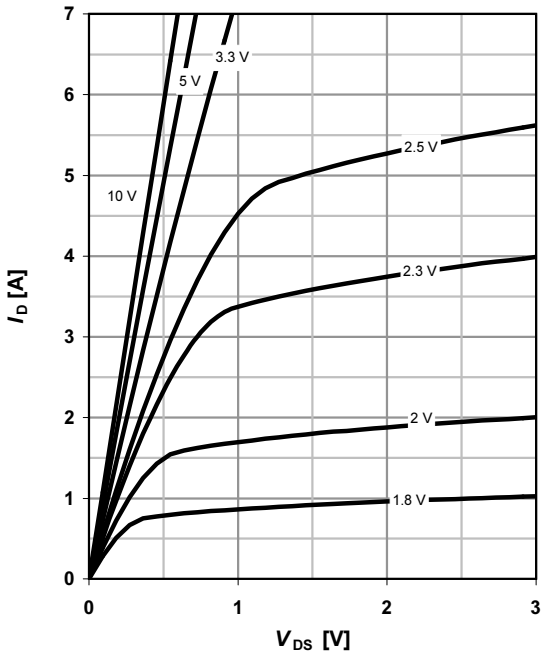
parameter: $D=t_p/T$



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

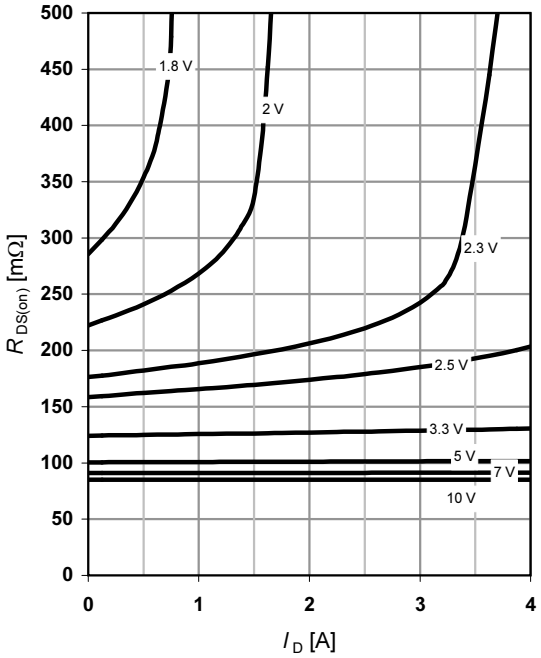
parameter: V_{GS}



6 Typ. drain-source on resistance

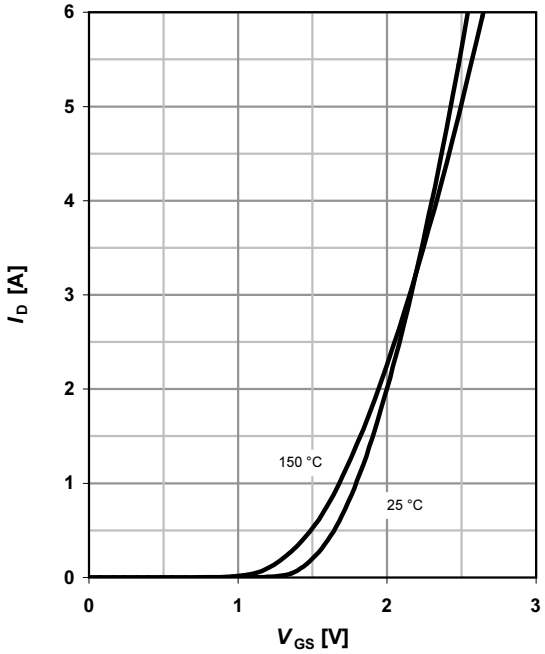
$R_{DS(on)}$=f(I_D); T_j=25 °C

parameter: V_{GS}



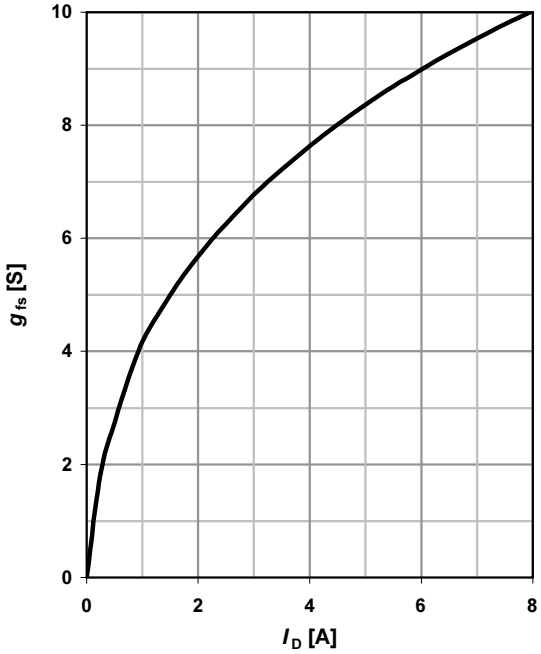
7 Typ. transfer characteristics

I_D=f(V_{GS}); |V_{DS}|>2|I_D|$R_{DS(on)max}$



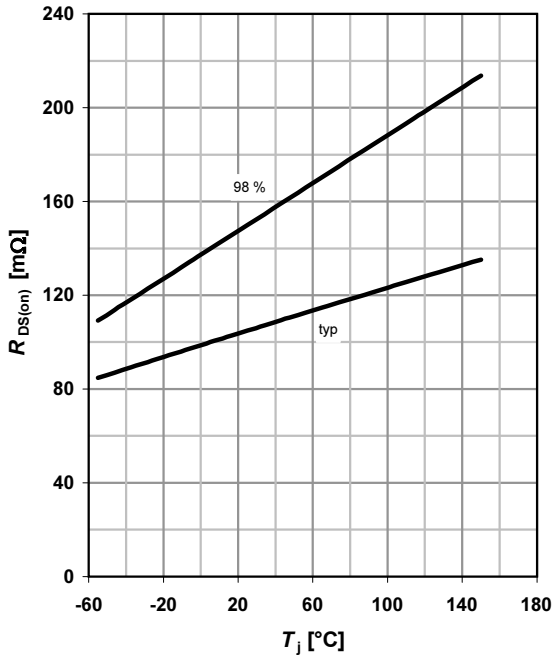
8 Typ. forward transconductance

g_{fs}=f(I_D); T_j=25 °C



9 Drain-source on-state resistance

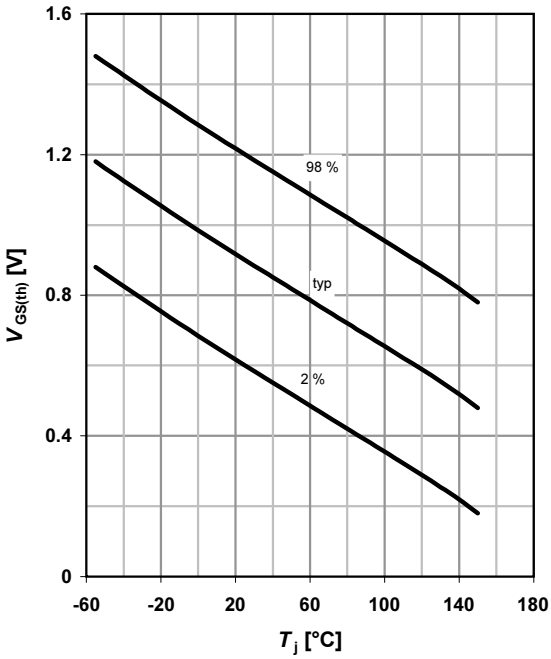
$R_{DS(on)}$=f(T_j); I_D=-1.5 A; V_{GS}=-4.5 V



10 Typ. gate threshold voltage

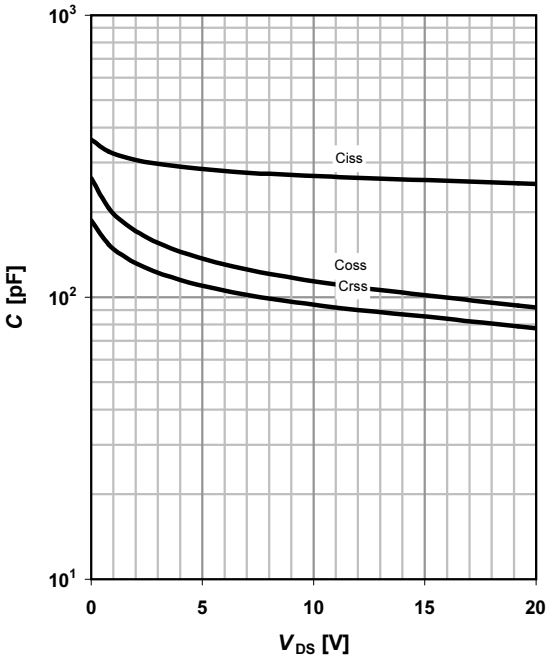
$V_{GS(th)}$=f(T_j); V_{DS}=V_{GS}; I_D=-11 µA

parameter: I_D



11 Typ. capacitances

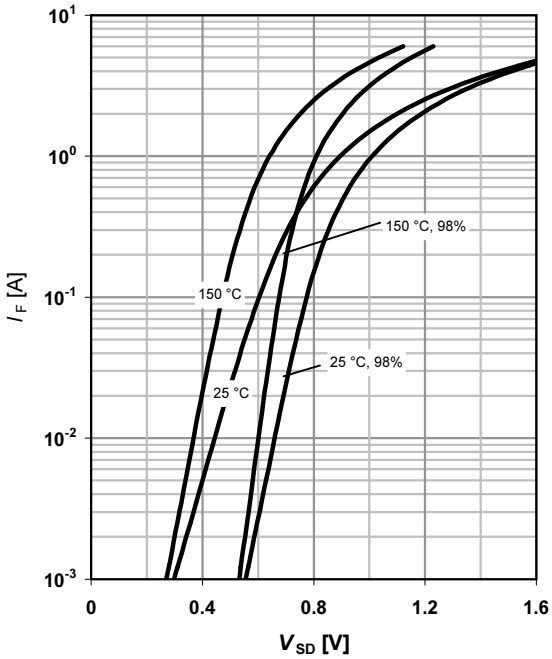
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz; T_j=25°C



12 Forward characteristics of reverse diode

I_F=f(V_{SD})

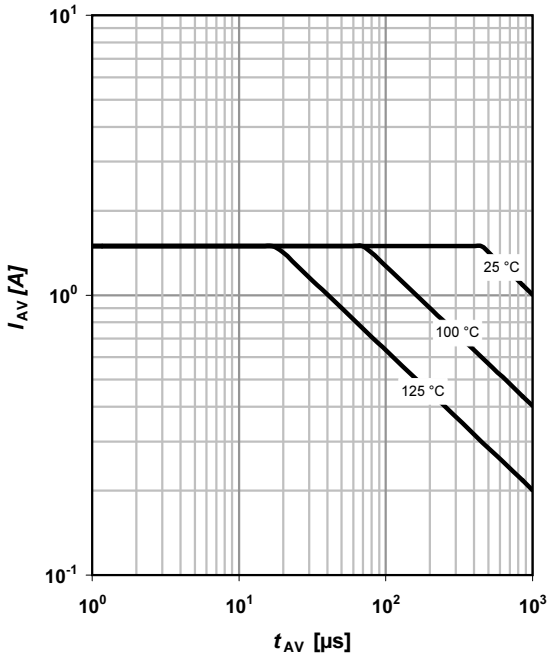
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

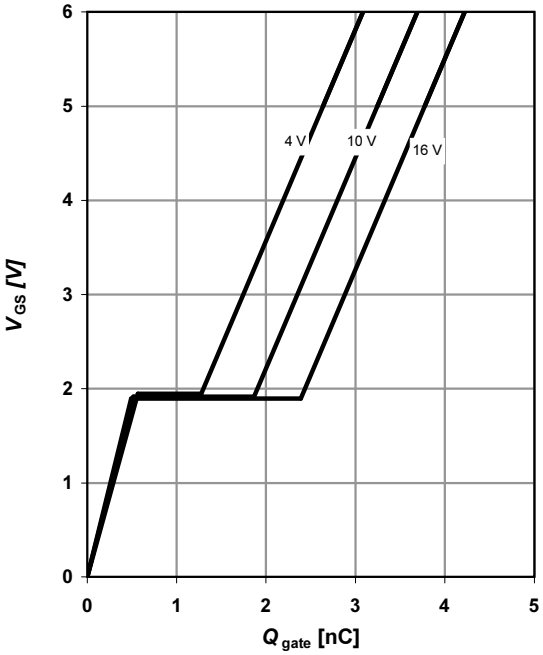
parameter: $T_{j(start)}$



14 Typ. gate charge

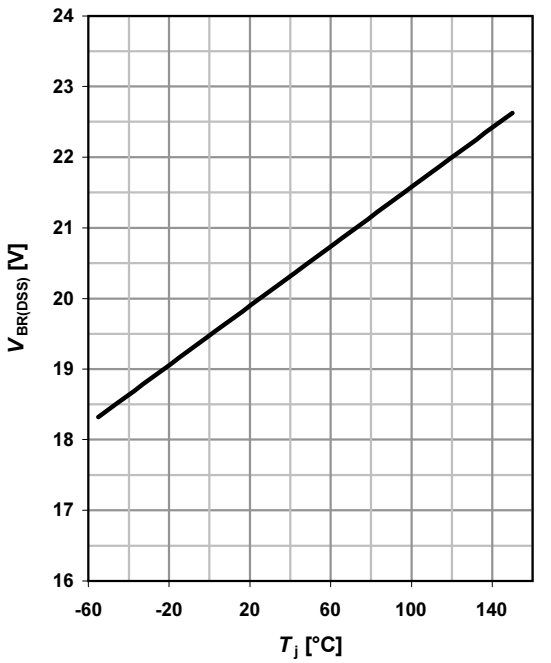
V_{GS}=f(Q_{gate}); I_D=-1.5 A pulsed

parameter: V_{DD}

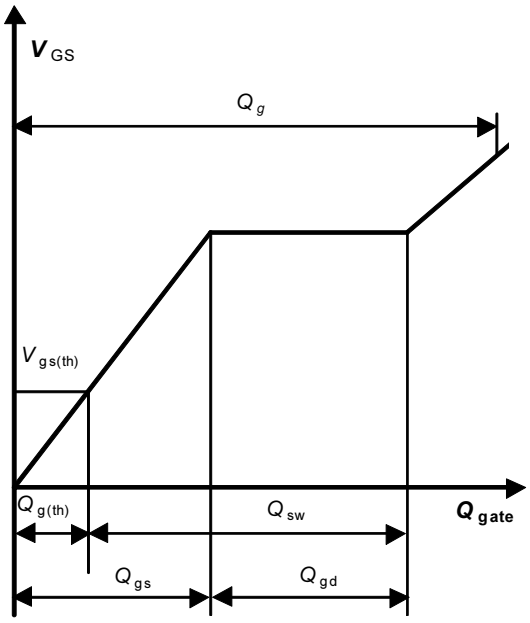


15 Drain-source breakdown voltage

$V_{BR(DSS)}$=f(T_j); I_D=250 µA

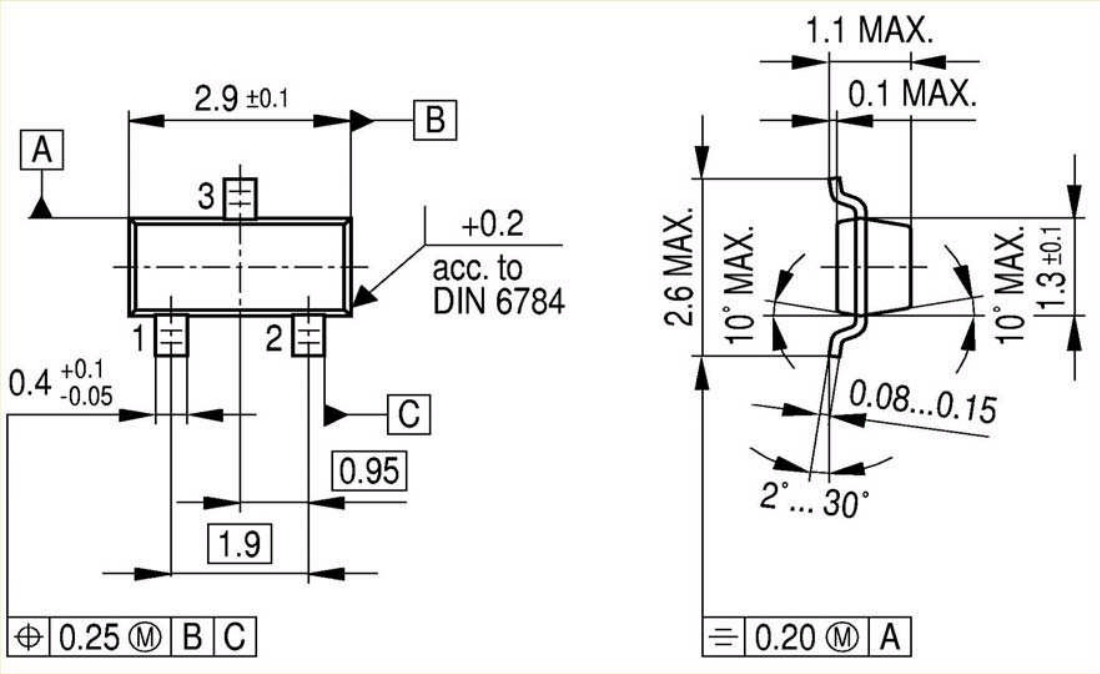


16 Gate charge waveforms

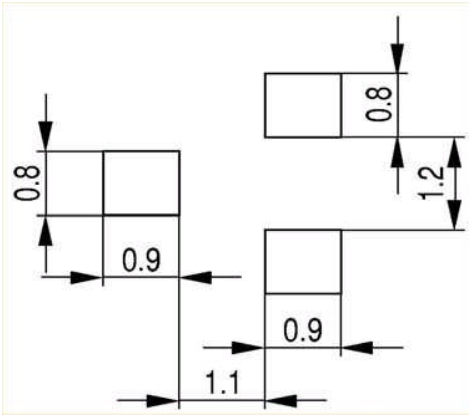


SOT23

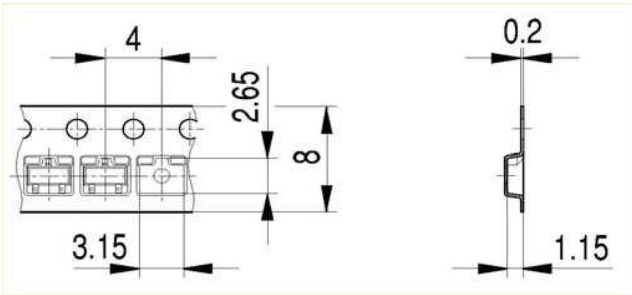
Package Outline:



Footprint:



Packaging:



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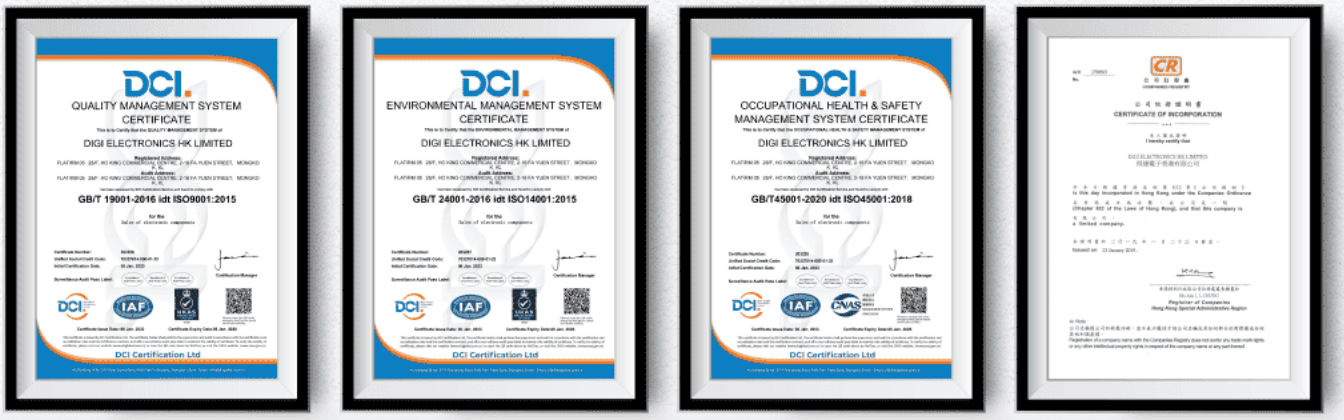

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